

# SSCL035N30TN4

#### **N-Channel Enhancement Mode MOSFET**

#### > Features

| V <sub>DS</sub> | V <sub>GS</sub> | R <sub>DS(ON)</sub> Typ. | l <sub>D</sub> |  |
|-----------------|-----------------|--------------------------|----------------|--|
| 201/            |                 | 3.5mΩ@10V                | 78A            |  |
| 30V             | ±20V            | 5.1mΩ@4.5V               | 70A            |  |

### Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent

RDSON with low gate charge. This device is suitable
for use in DC-DC conversion, power switch and
charging circuit.

#### 100% UIS + $\Delta VDS$ + Rg Tested!

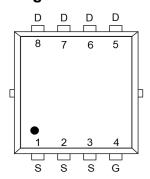
#### Applications

- Motor Drive Control
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

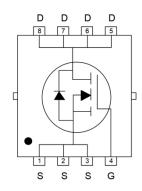
# Ordering Information

| Device        | Package        | Shipping  |  |
|---------------|----------------|-----------|--|
| SSCL035N30TN4 | PDFN3.3X3.3-8L | 5000/Reel |  |

# > Pin Configuration



PDFN3.3X3.3-8L (Top View)



**Pin Configuration** 



**Marking** 

(XXYY: Internal Traceability Code)



## ➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

| Symbol           | Parameter  | Ratings                   | Unit    |            |  |
|------------------|--|---------------------------|---------|------------|--|
| V <sub>DSS</sub> | Drain-to-Source Voltage                            |                           | 30      | V          |  |
| V <sub>GSS</sub> | Gate-to-Source Volta                               | ge                        | ±20     | V          |  |
|                  |  | 78                        | ^       |            |  |
| l <sub>D</sub>   | Continuous Drain Current                           | T <sub>C</sub> =100℃      | 49      | 1 A        |  |
|                  | Outliness Paris Outlines                           | T <sub>A</sub> =25℃       | 20      | ^          |  |
| IDSM             | Continuous Drain Current a                         | T <sub>A</sub> =70°C      | 16      | Α          |  |
| Ірм              | Pulsed Drain Curren                                | t <sup>b</sup>            | 312     | Α          |  |
| 5                | Daniel Division flore                              | Tc=25℃                    | 44      | 10/        |  |
| PD               | P <sub>D</sub> Power Dissipation <sup>c</sup>      | 18                        | W       |            |  |
|                  | Daniel Division flore                              | T <sub>A</sub> =25℃       | 2.9     | 10/        |  |
| P <sub>DSM</sub> | Power Dissipation <sup>a</sup>                     | T <sub>A</sub> =70°C      | 1.9     | W          |  |
| las              | Avalanche Current b L=0.5mH Single Pulse           |                           | 22      | Α          |  |
| Eas              | Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse |                           | 121     | mJ         |  |
| TJ               | Operation junction temperature                     |                           | -55~150 | °C         |  |
| T <sub>STG</sub> | Storage temperature ra                             | Storage temperature range |         | $^{\circ}$ |  |

## ➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

| Symbol         | Parameter                                | Ratings | Max. | Unit |
|----------------|--|---------|------|------|
| Reja           | Junction-to-Ambient Thermal Resistance a | 43      | 55   | °C/W |
| $R_{	heta JC}$ | Junction-to-Case Thermal Resistance      | 2.8     | 3.5  | C/VV |

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.0 www.sscsemi.com Analog Future



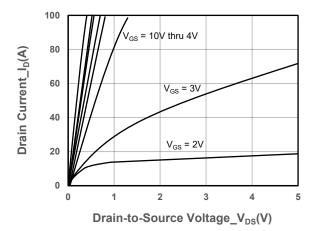
# SSCL035N30TN4

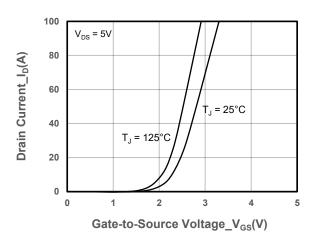
# $\succ$ Electrical Characteristics (T<sub>A</sub>=25 $^{\circ}$ C unless otherwise noted)

| Parameter                       | Symbol               | Test Conditions                               | Min. | Тур. | Max. | Unit |
|---------------------------------|----------------------|---|------|------|------|------|
| Drain-Source Breakdown Voltage  | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA  | 30   |      |      | V    |
| Gate Threshold Voltage          | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}$ , $I_D = 250$ uA            | 1.0  | 1.5  | 2.5  | V    |
| Drain Sauras On Basistanas      | D                    | V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A   |      | 3.5  | 4.8  | m0   |
| Drain-Source On-Resistance      | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A  |      | 5.1  | 6.8  | mΩ   |
| Zero Gate Voltage Drain Current | loss                 | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V   |      |      | 1    | μA   |
| Gate-Source Leak Current        | lgss                 | $V_{GS} = \pm 20V, V_{DS} = 0V$               |      |      | ±100 | nA   |
| Forward Voltage                 | V <sub>SD</sub>      | V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A    |      | 0.7  | 1.3  | V    |
| Gate Resistance                 | R <sub>G</sub>       | V <sub>DS</sub> = 0V, f = 1MHz                |      | 4.9  |      | Ω    |
| Input Capacitance               | C <sub>ISS</sub>     | \\ -15\\\\ -0\\                               |      | 936  |      |      |
| Output Capacitance              | Coss                 | $V_{DS} = 15V, V_{GS} = 0V,$<br>f = 1MHz      |      | 490  |      | pF   |
| Reverse Transfer Capacitance    | C <sub>RSS</sub>     | T - TIVIDZ                                    |      | 36   |      |      |
| Total Gate Charge               | Q <sub>G</sub>       | \\ -40\\\\ -45\\                              |      | 19   |      |      |
| Gate to Source Charge           | Q <sub>GS</sub>      | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, |      | 3    |      | nC   |
| Gate to Drain Charge            | Q <sub>GD</sub>      | I <sub>D</sub> = 20A                          |      | 3.4  |      |      |
| Turn-on Delay Time              | T <sub>D(ON)</sub>   |   |      | 5.5  |      |      |
| Rise Time                       | Tr                   | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, |      | 6    |      | Ī    |
| Turn-off Delay Time             | T <sub>D(OFF)</sub>  | $I_D = 20A, R_G = 3\Omega$                    |      | 14   |      | ns   |
| Fall Time                       | T <sub>f</sub>       |   |      | 6    |      |      |
| Diode Recovery Time             | Trr                  | I <sub>F</sub> =20A, di/dt=100A/us            |      | 13   |      | ns   |
| Diode Recovery Charge           | Qrr                  | I <sub>F</sub> =20A, di/dt=100A/us            |      | 21   |      | nC   |

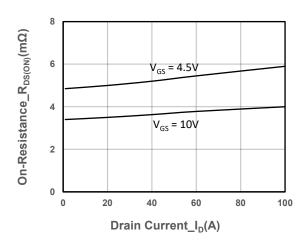


### > Typical Performance Characteristics (T<sub>A</sub>=25℃ unless otherwise noted)

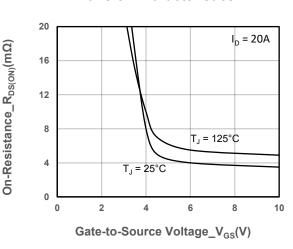




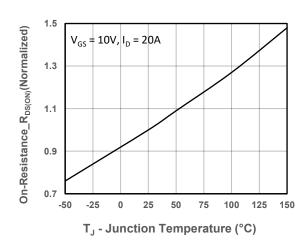
#### **Output Characteristics**



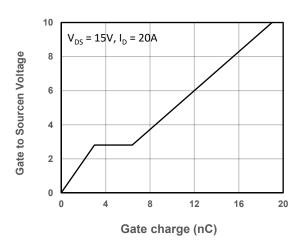
**Transfer Characteristics** 



#### On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

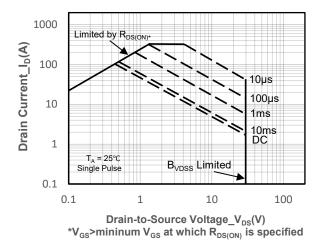


**On-Resistance vs. Junction Temperature** 

Gate-Source Voltage vs. Gate charge

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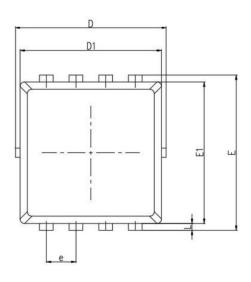


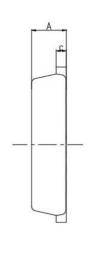


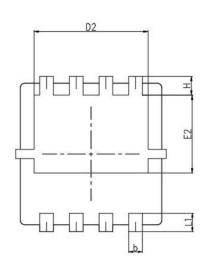
Safe Operating Area vs. Junction-to-Ambient

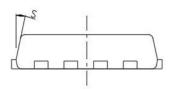


# Package Information









| Cymhol | MILL IMETER |      |      |  |
|--------|-------------|------|------|--|
| Symbol | Min         | Nom  | Max  |  |
| Α      | 0.65        | 0.75 | 0.9  |  |
| b      | 0.20        | 0.3  | 0.40 |  |
| С      | 0.1         | 1    | 0.22 |  |
| D      | 3.1         | 3.3  | 3.45 |  |
| D1     | 3           | 3.15 | 3.2  |  |
| D2     | 2.55        | 2.5  | 2.75 |  |
| E      | 3.15        | 3.3  | 3.45 |  |
| E1     | 2.9         | 3.05 | 3.2  |  |
| E2     | 1.55        | 1.75 | 1.95 |  |
| е      | 0.65BSC     |      |      |  |
| L      | 0.06        | 0.15 | 0.2  |  |
| L1     | 0.25        | 0.4  | 0.55 |  |
| Н      | 0.31        | 0.35 | 0.6  |  |
| S      | 10°         | 12°  | 14°  |  |



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